



H. Maejima et al.
501.20289RC6
S/9/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): **H. MAEJIMA ET AL.**
Serial No. : **09/704,529**
Filed: **November 3, 2000**
For: **WAFER HAVING CHAMFERED BEND PORTIONS
IN THE JOINT REGIONS BETWEEN THE CONTOUR
OF THE WAFER AND THE CUT-AWAY PORTION
OF THE WAFER**
Art Unit: **2823**
Examiner: **L. Pham**

AMENDMENT

Assistant Commissioner of Patents
Washington, D.C. 20231

April 30, 2002

Sir:

The following amendments and remarks are submitting in the above-
identified application in response to the Office Action mailed November 30,
2001.

IN THE CLAIMS

Please cancel claims 1, 2 and 4-13.

Please add new claims 14-44 as follows.

14. A process for producing a semiconductor device, comprising:
providing a wafer for forming an integrated circuit thereon, the wafer
having a main surface on which an integrated circuit is to be formed, a

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03 FC:103

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